



PK1172(v1.0) November 13, 2023

100% Material Declaration Data Sheet for XQZU49DR-FSRF1760

Average Weight : 18.5875 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die 1					0.706615	3.802%
	Silicon	7440-21-3	100.00	basis	0.706615	
Bump					0.020949	0.113%
	Polymer	N/A	16.07	PI	0.003367	
	Titanium	7440-32-6	0.04	UBM-sputter Ti	0.000009	
	Copper	7440-50-8	0.43	UBM-sputter Cu	0.000091	
	Nickel	7440-02-0	2.59	UBM-plating Ni	0.000542	
	Tin	7440-31-5	79.41	Bump-plating SnAg	0.016635	
	Silver	7440-22-4	1.46	Bump-plating SnAg	0.000305	
					0.074500	0.401%
Underfill	Bisphenol F type liquid epoxy resin	9003-36-5	15.00	basis	0.011175	
	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6	10.00	basis	0.007450	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	basis	0.003725	
	Amine type hardener	trade secret	10.00	basis	0.007450	
	Silicon dioxide	60676-86-0	58.00	filler	0.043210	
	Carbon black	1333-86-4	1.00	color agent	0.000745	
	Additives	trade secret	1.00	additives	0.000745	
					0.014336	0.077%
Solder paste	Tin	7440-31-5	54.50	metal	0.007813	
	Lead	7439-92-1	33.00	metal	0.004731	
	Organic amine	trade secret	4.90	metal	0.000702	
	Solvent	trade secret	4.90	flux	0.000702	
	Copolymer	trade secret	2.70		0.000387	
					0.385280	2.073%
Capacitor 1	Barium	12047-27-7	72.40	Ceramic	0.278943	
	Manganese	1313-13-9	10.60	Ceramic	0.040840	
	Nickel	7440-02-0	4.00	Internal Electrode	0.015411	
	Copper	7440-50-8	5.80	Termination	0.022346	
	Glass oxide	65997-17-3	0.20	Termination	0.000771	
	Nickel	7440-02-0	2.66	Plating	0.010248	
	Tin	7440-31-5	3.99	Plating	0.015373	
	Lead	7439-92-1	0.35	Plating	0.001348	
					8.199638	44.114%
Heat sink	Carbon	7440-44-0	0.08	Main material	0.655971	
	Silicon	7440-21-3	1.00	Main material	8.199638	
	Manganese	7439-96-5	2.00	Main material	16.399275	
	Phosphorus	7723-14-0	0.05	Main material	0.368984	
	Sulfur	7704-34-9	0.03	Main material	0.245989	
	Chromium	7440-47-3	20.00	Main material	163.992754	
	Nickel	7440-02-0	10.50	Main material	86.096196	
	Iron	7439-89-6	66.345	Main material	544.004962	
					0.061000	0.328%
Heat sink Adhesive	Treated Aluminium Oxide	None	80.00	Main material	0.048800	
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	20.00	Main material	0.012200	
					1.675163	9.012%
Solder ball	Tin	7440-31-5	63.00	Main material	1.055353	
	Lead	7439-92-1	37.00	Main material	0.619810	
					7.450049	40.081%
Substrate	Copper	7440-50-8	40.71		3.032984	
	Tin	7440-31-5	0.45		0.033228	
	Silver	N/A	0.26		0.019515	
	Core	N/A	39.28	Core	2.926125	
	Plugging	N/A	0.56	Via Plugging	0.041651	
	ABF	N/A	17.46	Build Up	1.300500	
	Solder Mask	N/A	1.29	Solder Mask	0.096046	

Revision History

Date	Version	Description of Revisions
11/13/2023	1.0	Initial AMD Release.

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